PATENT COOPERATION TREATY

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INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY (Charter II of the Patent Cooperation Treaty) RECEIVED

(Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

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Applicant's or agent's file reference P/63948/GPTU63	FOR FURTHER AC	CTION	See Form PCT/IPEA/416
international application No.	International filing date	(day/month/year)	Priority date (day/month/year)
PCT/EP2004/052616 21.10.2004			22.10.2003
International Patent Classification (I H01L21/58, H05K13/04	PC) or national classification and II	PC	
Applicant MARCONI COMMUNICATIO	ONS GMBH et al.		
This report is the international Authority under Article 35	onal preliminary examination re and transmitted to the applicar	eport, established by that according to Article	nis International Preliminary Examining 36.
2. This REPORT consists of	a total of 6 sheets, including t	his cover sheet.	
· · · · · · · · · · · · · · · · · · ·	panied by ANNEXES, comprisi		
	nt and to the International Bure		
☐ sheets of the cand/or sheets Administrative	containing rectifications author	ings which have been ized by this Authority (amended and are the basis of this report (see Rule 70.16 and Section 607 of the
☐ sheets which beyond the di Supplemental	sclosure in the international app	hich this Authority cor plication as filed, as in	nsiders contain an amendment that goes dicated in item 4 of Box No. I and the
sequence listing a	nd/or tables related thereto, in equence Listing (see Section 8)	computer readable for	ber of electronic carrier(s)) , containing monly, as indicated in the Supplemental e Instructions).
4. This report contains indic	ations relating to the following	items:	
☑ Box No. I Basis o	of the opinion		
☐ Box No. II Priority			
☐ Box No. III Non-es	stablishment of opinion with reg	ard to novelty, inventiv	ve step and industrial applicability
— • • • • • • • • • • • • • • • • • • •	funity of invention		
	ned statement under Article 35e bility; citations and explanation	(2) with regard to nove s supporting such stat	elty, inventive step or industrial tement
	documents cited		
	defects in the international ap		
Box No. VIII Certair	observations on the internatio	nal application	
Date of submission of the demand		Date of completion of	f this report
09.08.2005		14.12.2005	
Name and mailing address of the	international	Authorized Officer	es Peter
preliminary examining authority:			Agentin 11
D-10958 Berlin	ffice - Gitschiner Str. 103	Morena, E	
Tel. +49 30 25901 Fax: +49 30 25901	040	Telephone No. +49 3	30.25901-
Pax. +45 30 25501	- 840	relephone No. +43	20 COO I

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No. PCT/EP2004/052616

_	Box No. I Basis of the report			
1.	With regard to the language, this filed, unless otherwise indicated	th regard to the language , this report is based on the international application in the language in which it was ed, unless otherwise indicated under this item.		
	which is the language of a translational search (undernation of the international	slations from the original language into the following language, canslation furnished for the purposes of: er Rules 12.3 and 23.1(b)) tional application (under Rule 12.4) examination (under Rules 55.2 and/or 55.3)		
2.	Nith regard to the elements* of the international application, this report is based on <i>(replacement sheets which</i> have been furnished to the receiving Office in response to an invitation under Article 14 are referred to in this report as "originally filed" and are not annexed to this report):			
	Description, Pages			
	1-12	as originally filed		
	Claims, Numbers			
	1-10	as originally filed		
	Drawings, Sheets	•		
	1/3-3/3	as originally filed		
	□ a sequence listing and/or any related table(s) - see Supplemental Box Relating to Sequence Listing			
3.	The amendments have resulted in the cancellation of: ☐ the description, pages ☐ the claims, Nos. ☐ the drawings, sheets/figs ☐ the sequence listing (specify): ☐ any table(s) related to sequence listing (specify):			
4.	☐ This report has been establicated not been made, since they had	ecify):		
	t If item 4 emplies so	ome or all of these sheets may be marked "superseded "		

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

International application No. PCT/EP2004/052616

Box No. V Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

1. Statement

Novelty (N)

Yes: Claims

1-10

No: Claims

Inventive step (IS)

Yes: Claims

1-10

No: Claims

Industrial applicability (IA)

Yes: Claims

1-10

No: Claims

2. Citations and explanations (Rule 70.7):

see separate sheet

Box No. VII Certain defects in the international application

The following defects in the form or contents of the international application have been noted:

see separate sheet

Box No. VIII Certain observations on the international application

The following observations on the clarity of the claims, description, and drawings or on the question whether the claims are fully supported by the description, are made:

see separate sheet

Re Item V

Reasoned statement with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

- 1 In this Written Opinion reference is made to the following documents cited in the International Search Report:
 - D1: US-B1-6 471 110 (LUECHINGER CHRISTOPH ET AL) (2002-10-29)
 - D2: PATENT ABSTRACTS OF JAPAN vol. 2000, no. 14, (2001-03-05) & JP 2000 332495 A (SONY CORP), 30 November 2000 (2000-11-30)
 - D3: US 2001/037855 A1 (TAKESHITA NAOKI ET AL) (2001-11-08)
 - D4: US-A-6 146 912 (TIGHE ET AL) (2000-11-14)
 - D5: PATENT ABSTRACTS OF JAPAN vol. 016, no. 312 (E-1230), (1992-07-09) & JP 04 087346 A (NIPPON STEEL CORP), 19 March 1992 (1992-03-19)
- The document D1 is regarded as being the closest prior art to the subject-matter of independent claim 1 and discloses a method for gluing a circuit component to a circuit substrate comprising the steps of:
 - a) seizing a circuit component using a gripper (see D1, column 2, lines 2-3);
- b) moving the gripper towards the surface of the circuit substrate to a target distance from the surface at which adhesive applied between the circuit component and the circuit substrate is pressed (see D1, column 2, lines 4-6; lines 11-15, figure 1b);
- c) releasing the circuit component (see D1, column 2, line 9) and removing the gripper from the circuit component (see D1, column 2, line 10). The method disclosed by document D1 further includes a controlled up and down movement of the semiconductor chip, by means of which possible bubbles contained within the solder are removed (see D1, column 2, lines 31-60) and the parallelism between the chip and the substrate is increased (see D1, column 4, lines 15-31).

The subject-matter of claim 1 differs from this known method in that after releasing the circuit component, the gripper is:

- d) turned around an axis perpendicular to the surface of the circuit substrate;
- e) moved into the target distance again; and

INTERNATIONAL PRELIMINARY **REPORT ON PATENTABILITY** (SEPARATE SHEET)

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f) removed again.

The subject-matter of claim 1 is therefore new (Article 33(2) PCT).

The problem to be solved by the present invention may be regarded as to correct a possible residual misalignment between the component and the substrate. The solution to this problem proposed in claim 1 of the present application is considered as involving an inventive step (Article 33(3) PCT) for the following reasons:

- a) document D1 does not disclose nor suggest to turn the gripper after releasing the circuit component and to further bring it in contact with the device so as to correct a possible residual misalignment;
- b) document D2 discloses how a due rotation of the circuit component in the aligning phase affects the co-planarity of the circuit component with the mounting surface (see D2, paragraphs 20-22, figure 5); however, document D2 does not suggest to exploit the rotation of the gripper in order to correct the parallelism of the circuit component during the mounting phase;
- c) documents D3-D5 suggests completely different solutions to provide a good parallelism between the device component and the circuit substrate.
- Claims 2-10 are dependent on claim 1 and as such also meet the requirements of the 3 PCT with respect to novelty and inventive step.
- 4 All claims 1-10 are considered as industrially applicable, and therefore they meet the criteria of Article 33(4) PCT.

Re Item VII

Certain defects in the international application

1 Contrary to the requirements of Rule 5.1(a)(ii) PCT, the relevant background art disclosed in the documents D1-D5 is not mentioned in the description, nor are these documents identified therein.

Re Item VIII

Certain observations on the international application

- 1 It is clear from the description (see description, page 4, line 19 page 5, line 10) that the following feature is essential to the definition of the invention:
 - (1) when the griper is moved in the target distance for the second time it comes in contact with the circuit component; more precisely, in step b) the local coordinates of the gripper in the target distance are detected and in step e) the gripper is in the same local coordinates as in step b).

Since independent claim 1 does not contain this feature it does not meet the requirement following from Article 6 PCT taken in combination with Rule 6.3(b) PCT that any independent claim must contain all the technical features essential to the definition of the invention.